- Digital Design Avoids Analog Compensation Errors
- Easily Cascadable for Higher Order Loops
- Useful Frequency from DC to: 50 MHz Typical (K Clock) 35 MHz Typical (I/D Clock)

#### description

The SN54LS297 and SN74LS297 devices are designed to provide a simple, cost-effective solution to high-accuracy, digital, phase-locked-loop applications. These devices contain all the necessary circuits, with the exception of the divide-by-N counter, to build first order phase-locked loops as described in Figure 1.

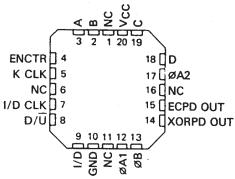
Both exclusive-OR (XORPD) and edge-controlled (ECPD) phase detectors are provided for maximum flexibility.

Proper partitioning of the loop function, with many of the building blocks external to the package, makes it easy for the designer to incorporate ripple cancellation or to cascade to higher order phase-locked loops.

The length of the up/down K counter is digitally programmable according to the K counter function table. With A, B, C, and D all low, the K counter is disabled. With A high and B, C, and D low, the K counter is only

SN54LS297 . . . J OR W PACKAGE SN74LS297 . . . N PACKAGE (TOP VIEW) B 1 16 VCC 15 □ C 2 ENCTR [ 14 🛮 D 3 K CLK □4 13 ØA2 I/D CLK 5 12 ECPD OUT D/U∏6 11 XORPD OUT 10 ØB I/D OUT 7 GND 8 9 ØA1

SN54LS297 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

three stages long, which widens the bandwidth or capture range and shortens the lock time of the loop. When A, B, C, and D are all programmed high, the K counter becomes seventeen stages long, which narrows the bandwidth or capture range and lengthens the lock time. Real-time control of loop bandwidth by manipulating the A through D inputs can maximize the overall performance of the digital phase-locked loop.

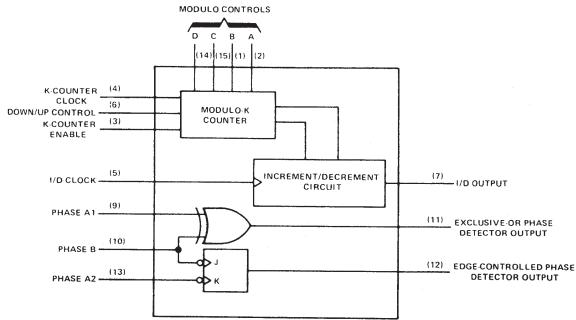


FIGURE 1-SIMPLIFIED BLOCK DIAGRAM

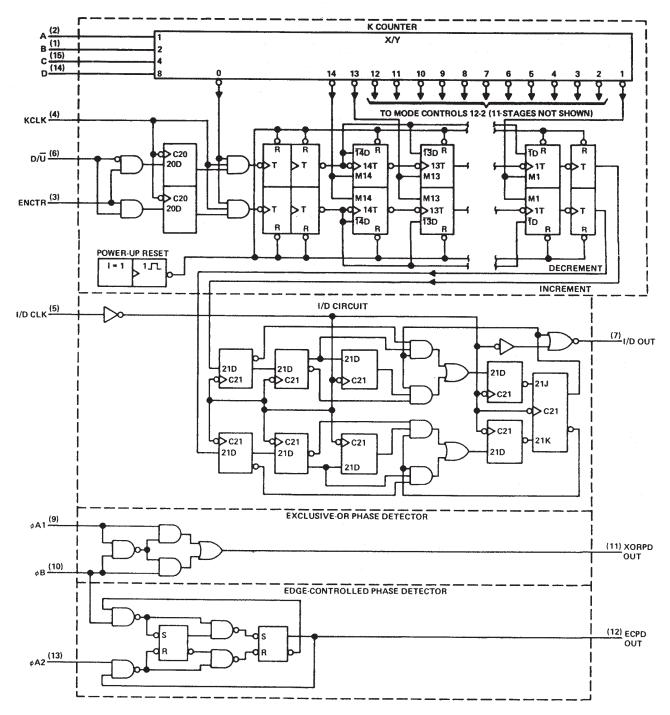
Pin numbers shown are for J, N and W packages.



#### description (continued)

The 'LS297 can perform the classic first-order phase-locked loop function without using analog components. The accuracy of the digital phase-locked loop (DPLL) is not affected by VCC and temperature variations, but depends solely on accuracies of the K clock, I/D clock, and loop propagation delays. The I/D clock frequency and the divide-by-N modulos will determine the center frequency of the DPLL. The center frequency is defined by the relationship  $f_C = I/D$  Clock/2N (Hz).

### logic diagram (positive logic)



Pin numbers shown are for J, N, and W packages.



# K COUNTER FUNCTION TABLE (DIGITAL CONTROL)

D	С	В	Α	MODULO (K)
Ł	L	L	L	Inhibited
L	L	L	Н	23
L	L	H - 1	· · L	2 <sup>4</sup> 2 <sup>5</sup>
٦	L	Н	Н	
L	Н	L	L	26
L	н	L	Н.	27
L	н	н	L	28
Ł	н	н	н	29
Н	L	L	L	210
н	L	L	н	211
н	L	н	L	212
н	L	н	н	213
Н	н	L	L	214
н	н	L	н	215
н	н	н	L	216
н	н	н	н	217

# FUNCTION TABLE EXCLUSIVE-OR PHASE DETECTOR

φΑ1	φВ	XORPD OUT
L	 L	L
L	н	н
• н	L	And American
н	н	٠.

# FUNCTION TABLE EDGE-CONTROLLED PHASE DETECTOR

φ <b>А2</b>	φВ	ECPD OUT
H or L	1	н
4	H or L	L
H or L	<b>↑</b>	No change
1	H or L	No change
1		

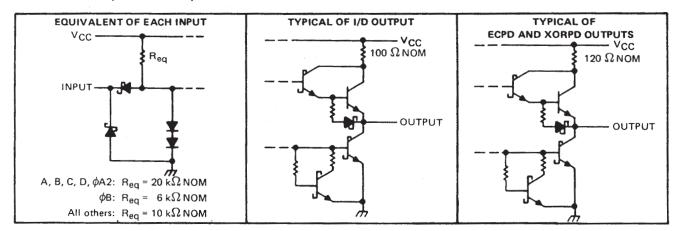
H = steady-state high level

L = steady-state low level

# = transition from high to low

t = transition from low to high

#### schematics of inputs and outputs



#### operation

The phase detector generates an error signal waveform that, at zero phase error, is a 50% duty cycle square wave. At the limits of linear operation, the phase detector output will be either high or low all of the time, depending on the direction of the phase error  $(\phi_{in} - \phi_{out})$ . Within these limits, the phase detector output varies linearly with the input phase error according to the gain  $k_d$ , which is expressed in terms of phase detector output per cycle of phase error. The phase detector output can be defined to vary between  $\pm 1$  according to the relation:

$$PD Output = \frac{\% high - \% low}{100}$$
 (1)

The output of the phase detector will be  $k_d \phi_e$ , where the phase error  $\phi_e = \phi_{in} - \phi_{out}$ .

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Exclusive-OR phase detectors (XORPD) and edge-controlled phase detectors (ECPD) are commonly used digital types. The ECPD is more complex than the XORPD logic function, but can be described generally as a circuit that changes states on one of the transitions of its inputs.  $k_d$  for an XORPD is 4 because its output remains high (PD output = 1) for a phase error of 1/4 cycle. Similarly,  $k_d$  for the ECPD is 2 since its output remains high for a phase error of 1/2 cycle. The type of phase detector will determine the zero-phase-error point, i.e., the phase separation of the phase detector inputs for  $\phi_e$  defined to be zero. For the basic DPLL system of Figure 2,  $\phi_e$  = 0 when the phase detector output is a square wave. The XORPD inputs are 1/4 cycle out of phase for zero phase error. For the ECPD,  $\phi_e$  = 0 when the inputs are 1/2 cycle out of phase.

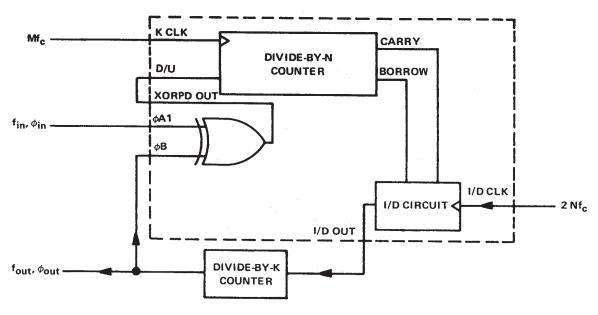


FIGURE 2-DPLL USING EXCLUSIVE-OR PHASE DETECTION

The phase detector output controls the up/down input to the K counter. The counter is clocked by input frequency  $Mf_C$ , which is a multiple M of the loop center frequency  $f_C$ . When the K counter recycles up, it generates a carry pulse. Recycling while counting down generates a borrow pulse. If the carry and borrow outputs are conceptually combined into one output that is positive for a carry and negative for a borrow, and if the K counter is considered as a frequency divider with the ratio  $Mf_C/K$ , the output of the K counter will equal the input frequency multiplied by the division ratio. Thus the output from the K counter is  $(k_d \phi_e Mf_C)/K$ .

The carry and borrow pulses go to the increment/decrement (I/D) circuit, which, in the absence of any carry or borrow pulse, has an output that is 1/2 of the input clock I/D CLK. The input clock is just a multiple, 2N, of the loop center frequency. In response to a carry or borrow pulse, the I/D circuit will either add or delete a pulse at I/D OUT. Thus the output of the I/D circuit will be Nf<sub>c</sub> +  $(k_d\phi_e Mf_c)/2K$ .

The output of the N counter (or the output of the phase-locked loop) is thus:

$$f_0 = f_c + (k_d \phi_e M f_c)/2KN$$

If this result is compared to the equation for a first-order analog phase-locked loop, the digital equivalent of the gain of the VCO is just  $Mf_c/2KN$  or  $f_c/K$  for M=2N.

Thus the simple first-order phase-locked loop with an adjustable K counter is the equivalent of an analog phase-locked loop with a programmable VCO gain.



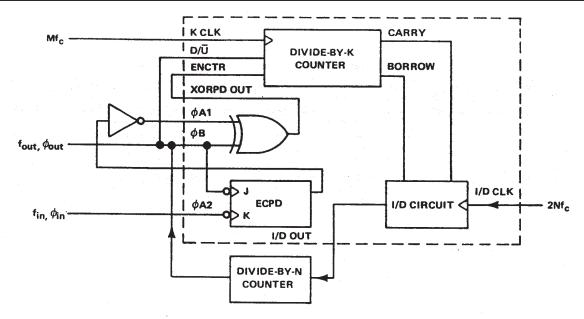


FIGURE 3-DPLL USING BOTH PHASE DETECTORS IN A RIPPLE-CANCELLATION SCHEME

# absolute maximum rating over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
Input voltage		7 V
Operating free-air temperature range: §	SN54LS297	- 55° C to 125° C
5	SN74LS297	0°C to 70°C
Storage temperature range	· · · · · · · · · · · · · · · · · · ·	- 65° C to 150° C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

			S	SN54LS297			SN74LS297			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V	
IOH IOL fclock tw tsu, to K th	High-level output current	I/D OUT			- 1.2			- 1.2	mA	
		EXOR, ECPD			- 400			- 400	μА	
loi	Low-level output current	I/D OUT			12			24	mA	
,OL	Low-level output current	XOR, ECPD			4			8	mA	
falaak	Clock frequency	K Clock	0		32	0		32	MHz	
CIOCK		I/D Clock	0		16	0		16	MHz	
t	Width of clock input pulse	K Clock	16			16			ns	
·w	Width of clock input pulse	I/D Clock	33			33			ns	
t <sub>su</sub> , to K	Setup time to K Clock 1	U/D;ENCTR	. 30			30		****	ns	
th	Hold time from K Clock †	U/D, ENCTR	0			0			ns	
TA	Operating free-air temperature		- 55		125	0		70	°C	



## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†			S	N54LS2	97	SN74LS297			
			TEST CORDITIONS				TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input ve	oltage				2	and the second	ata (	2			V
VIL	Low-level input vo	oltage						0.7			0.8	V
VIK	Input clamp volta	ge	V <sub>CC</sub> = MIN,	V <sub>CC</sub> = MIN, I <sub>1</sub> = -18 mA				-1.5			-1.5	V
Vон	High-level	I/D OUT	VCC = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OH</sub> = MAX	2.4			2.4			
* On	output voltage	Others	VIL = VIL max		IOH = MAX	2.5			2.7			٧
VOL		I/D OUT			IOL = 12 mA		0.25	0.4		0.25	0.4	
	Low-level output voltage	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	IOL = 24 mA					0.35	0.5	
		Others	VIL = VIL max		10L = 4 mA		0.25	0.4		0.25	0.4	<del>.</del>
					IOL = 8 mA					0.35	0.5	İ
Ц	Input current at maximum input voltage		V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mA
1 <sub>1H</sub>	High-level	U/D, EN, φΑ1 φΒ	V <sub>CC</sub> = MAX,	V 2.7.V				40			40	
'IH	input current	All others	ACC - MAX	V   - 2.7 V				60 20			60 20	μΑ
1	Low-level	U/Ō, EN, ΦΑ1 ΦΒ	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V				- 0.8			- 0.8	
۱۱۲	input current	All others	$V_1 = 0.4 V$					-1.2 - 0.4			-1.2 - 0.4	mA
los	Short-circuit	I/D OUT	V <sub>CC</sub> = MAX	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		-30		-130	-30		-130	4
-03	output current §	Others	VCC - WAA					-100	-20		-100	mA
<sup>1</sup> cc	Supply current		V <sub>CC</sub> = MAX, All outputs open	All inputs gro	unded,		75	120		75	120	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

PARAMETER¶	FRO	M (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
,	KCLK		I/D OUT		32	50		
f <sub>max</sub>	I/D CLK		I/D OUT	R <sub>L</sub> = 667 Ω,	16	35		MHz
t <sub>PLH</sub>	I/D CLK †		I/D OUT	CL = 45 pF,		15	25	ns
tPHL.	I/D CLK †		I/D OUT	See Note 2		22	35	ns
t <sub>PLH</sub>	$\phi$ A1 or $\phi$ B	Other input low	XOR OUT			10	15	ns
PLH	φΑ1 or <b>φ</b> Β	Other input high	XOR OUT	1		17	25	
****	φA1 or φB Other input low		XOR OUT	R <sub>L</sub> = 2 kΩ,		15	25	
tPHL -	$\phi$ A1 or $\phi$ B Other input high $\phi$ B $\downarrow$ $\phi$ A2 $\downarrow$		XOR OUT	C <sub>L</sub> = 45 pF, See Note 2		17	25	ns
tPLH .			ECPD OUT			20	30	ns
tPHL			ECPD OUT			20	30	ns

 $<sup>\</sup>mathbf{1}_{tpLH}$  = propagation delay time, low-to-high-level output



 $<sup>\</sup>ddagger$ All typical values are of  $V_{CC}$  = 5 V,  $T_{A}$  = 25°C.

<sup>§</sup> Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

tpHL = propagation delay time, high-to-low-level output

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



#### PACKAGE OPTION ADDENDUM

10-Jun-2014

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS297N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS297N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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10-Jun-2014

## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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